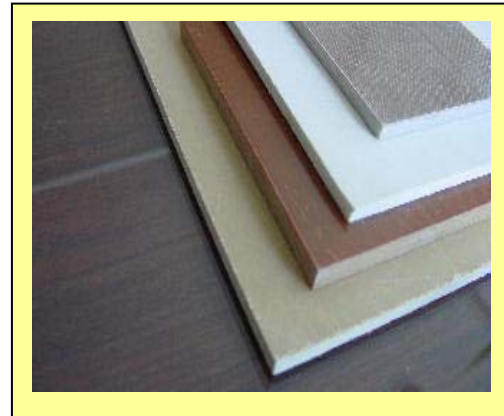


## High Compression Strength Board For Press Platen Mold Insulation

This series of boards are designed to offer heat and compressive resistance that are required in heating mold insulation.

Advantages of the boards are:

1. contain no asbestos or any other toxic materials
2. low thermal conductivity
3. high strength at processed temperature
4. very low water/moisture absorption,



本系列係專為高溫**模具保溫斷熱**而發展製造之耐高溫高強度複合板材，與目前市面上所使用之纖維水泥板，或矽酸鈣板比較，將帶給您下列特性:

1. 不含石棉或其它有害物質
2. 低熱傳導率
3. 於操作溫度下高抗壓及衝擊強度 (Impact Strength)
4. 非常低之水份吸收率 (不龜裂)

## Data and Availability

代號 Grade	550HT	C900MHT	G330	M40
連續使用溫度 continuous temperature resistance (°C)	200	500	170	200
比重 Specific Gravity	1.95	2.15	1.97	1.2
熱傳導係數 Thermal Conductivity (W/m.k.)	0.27	0.3	--	0.167
抗壓強度 Compression Strength (Kg/cm <sup>2</sup> )				
25 °C	3450	4080	1900	1276(25°C)
200 °C	1267	2500	--	1356(204°C)
288°C	1197	--	--	1405(260°C)
撓曲強度 Flexural Strength (Kg/cm <sup>2</sup> )	2183	2340	3600	1452
耐衝擊強度 Izod Impact Strength(J/cm)	4.3	--	5.95	4.8
吸水率 Water Absorption, (%)	0.2	<1	0.66	0.25
厚度範圍 Thickness range(mm)	6.35-31.25	5- 25	6.35, 12.7	6.35-31.25
厚度公差 Thickness Tolerance (mm)	+/-0.05	--	--	+/-0.05
板面呎吋 Sheet sizes (m x m)	1.25x2.45	1.0x1.2	1.22x1.83	1.23x2.50

## Your Solution for Thermal Insulation Since 1989

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